

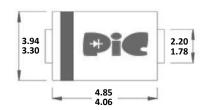
Features

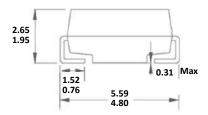
- The plastic package carries Underwriters Laboratory Flammability Classification 94V-O
- For surface mounted applications
- Low reverse leakage
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 250°C/10 seconds at terminals
- Glass passivated chip junction

Mechanical Data

- Case: JEDEC DO-214AA molded plastic body over passivated chip
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any

SMB





Dimensions in inches and millimeters



Maximum Ratings & Electrical Characteristic

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter		Symbol	S2AB	S2BB	S2DB	S2GB	S2JB	S2KB	S2MB	UNITS
Marking Code			S2AB	S2BB	S2DB	S2GB	S2JB	S2KB	S2MB	-
Recurrent Peak Reverse Voltage			50	100	200	400	600	800	1000	Volts
RMS Voltage		V_{RMS}	35	70	140	280	420	560	700	Volts
DC Blocking Voltage		V _R	50	100	200	400	600	800	1000	Volts
Average Forward Rectified Current		I _{F(AV)}	2.0						Amps	
Peak Forward Surge Current: 8.3ms single half sine -wave superimposed on rated load		I _{FSM}	50						Amps	
Forward Voltage at 2.0A		V _F	1.15					Volts		
DC Reverse Current at Rated DC Blocking Voltage	T _J =25 °C	I _R				5				μА
Typical Junction Capacitance (NOTE1) C _J		15						pF		
Typical thermal Resistance (NOTE2)		R _{OJA}	75					°C/W		
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55 to +150						οС	

Notes:

- (1) Measured at 1MHZ and applied reverse voltage of 4.0V D.C.
- (2) P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas





Rating and Characteristics Curves

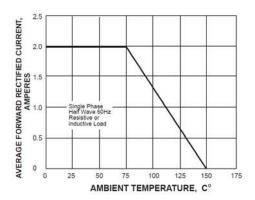


Fig. 1 Forward Current Derating Curve

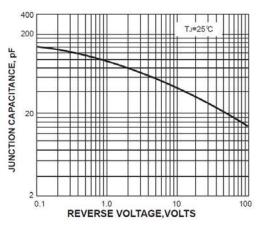


Fig. 3 Typical Junction Capacitance

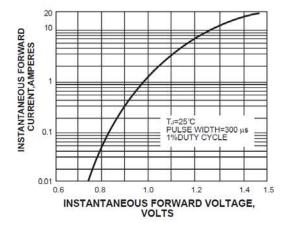


Fig. 5 Typical Instantaneous Forward Characteristics

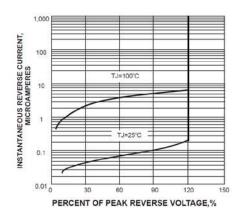


Fig. 2 Typical Reverse Characteristics

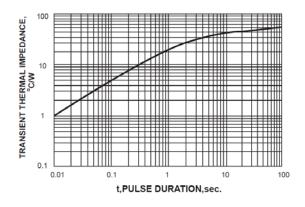


Fig. 4 Typical Transient Thermal Impedance

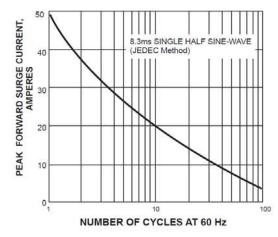
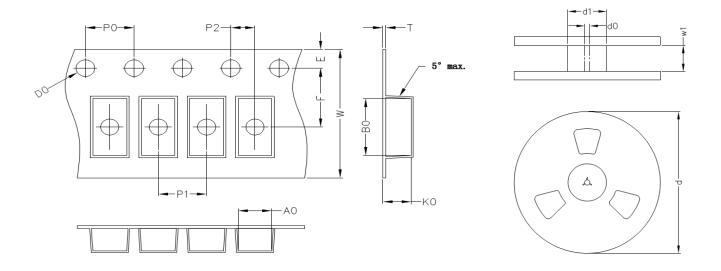


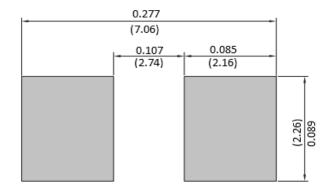
Fig. 6 Max. Non Repetitive Peak Forward Surge Current



Packaging Specifications											
Daalaasa	A0	В0	K0	D0	Е	F	P0	P1	P2	Т	W
Package	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)
SMA	2.8±0.1	5.33±0.1	2.36±0.1	1.55±0.1	1.75±0.1	5.50±0.1	4.0±0.1	4.0±0.01	2±0.1	0.25±0.1	9.4±0.1
SMB	3.8±0.1	5.40±0.1	2.45±0.1	1.55±0.1	1.75±0.1	5.50±0.1	4.0±0.1	8.0±0.01	2±0.1	0.25±0.1	9.4±0.1
SMC	6.05±0.1	8.31±0.1	2.54±0.1	1.55±0.1	1.75±0.1	7.50±0.1	4.0±0.1	8.0±0.05	2±0.1	0.25±0.1	12±0.1



Suggested Pad Layout



Package	D1 (mm)	D0 (mm)	W1 (mm)	D (mm)
SMA	75	13.5	13.5	330
SMB	75	13.5	13.5	330
SMC	75	13.5	17.0	330

NOTE: The tolerance of reel is ±2mm

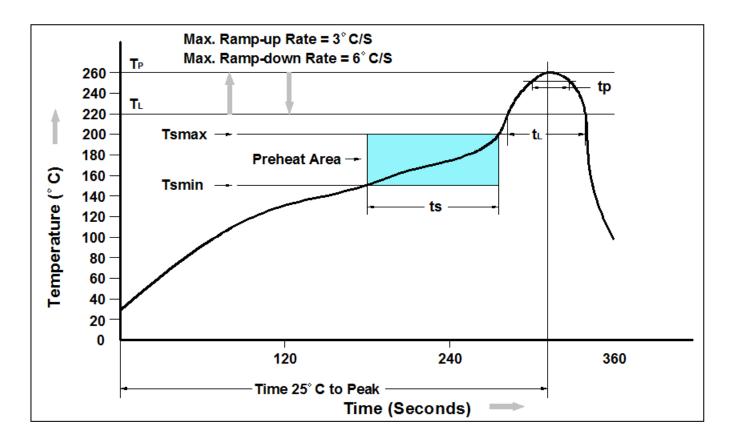
Unit: inch (mm)

Ordering Information

Part Number	Description	Quantity
S2AB~S2MB	SMB Reel	3000 pcs



Recommand IR Reflow Soldering Thermal Profile



Profile Feature	Pb-Free Assembly Profile			
Temperature Min. (Tsmin)	150°C			
Temperature Max. (Tsmax)	200°C			
Time (ts) from (Tsmin to Tsmax)	60-120 seconds			
Average Ramp-up Rate (tLto tP)	3°C/second max.			
Liquidous Temperature (TL)	217°C			
Time (tL) Maintained Above (TL)	60 – 150 seconds			
Peak Temperature	260°C +0°C / -5°C			
Time (tP) within 5°C of actual Peak Temperature	30 seconds			
Ramp-down Rate (TP to TL)	6°C/second max			
Time 25°C to Peak Temperature	8 minutes max.			





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